HiPerFRED

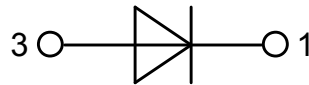|		
V_{RRM}	=	600 V
I_{FAV}	=	15 A
t_{rr}	=	35 ns

High Performance Fast Recovery Diode
Low Loss and Soft Recovery
Single Diode

Part number

DSEP15-06A

Backside: cathode

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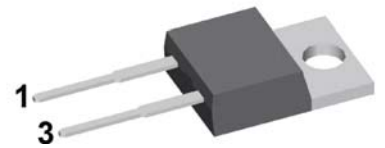
Features / Advantages:
- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
  - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:
- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: TO-220
- Industry standard outline
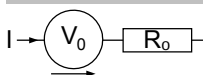- RoHS compliant
- Epoxy meets UL 94V-0

Data according to IEC 60747and per semiconductor unless otherwise specified   20120318a

Fast Diode

Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RSM}	*max. non-repetitive reverse blocking voltage*	T_{VJ} = 25°C				600	V
V_{RRM}	*max. repetitive reverse blocking voltage*	T_{VJ} = 25°C				600	V
I_R	*reverse current, drain current*	V_R = 600 V	T_{VJ} = 25°C			100	µA
		V_R = 600 V	T_{VJ} = 150°C			0.5	mA
V_F	*forward voltage drop*	I_F = 15 A	T_{VJ} = 25°C			2.04	V
		I_F = 30 A				2.25	V
		I_F = 15 A	T_{VJ} = 150°C			1.35	V
		I_F = 30 A				1.59	V
I_{FAV}	*average forward current*	T_C = 140°C	T_{VJ} = 175°C			15	A
		rectangular d = 0.5					
V_{F0}	*threshold voltage*	} *for power loss calculation only*	T_{VJ} = 175°C			0.99	V
r_F	*slope resistance*					15	mΩ
R_{thJC}	*thermal resistance junction to case*					1.6	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.50		K/W
P_{tot}	*total power dissipation*	T_C = 25°C				95	W
I_{FSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine; V_R = 0 V	T_{VJ} = 45°C			110	A
C_J	*junction capacitance*	V_R = 400 V f = 1 MHz	T_{VJ} = 25°C		12		pF
I_{RM}	*max. reverse recovery current*	} I_F = 15 A; V_R = 300 V -di$_F$/dt = 200 A/µs	T_{VJ} = 25°C		5		A
			T_{VJ} = 100°C		7		A
t_{rr}	*reverse recovery time*		T_{VJ} = 25°C		35		ns
			T_{VJ} = 100°C		95		ns
E_{AS}	*non-repetitive avalanche energy*	I_{AS} = 1 A L = 180 µH	T_{VJ} = 25°C			0.1	mJ
I_{AR}	*repetitive avalanche current*	V_A = 1.5·V_R typ.: f = 10 kHz				0.1	A

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Package	TO-220		Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			35	A
T_{stg}	storage temperature		-55		150	°C
T_{VJ}	virtual junction temperature		-55		175	°C
Weight				2		g
M_D	mounting torque		0.4		0.6	Nm
F_C	mounting force with clip		20		60	N

Product Marking

Part Number → abcdef

Logo → IXYS → YYWW Z

Date Code

Lot # → XXXXXX

Assembly Line
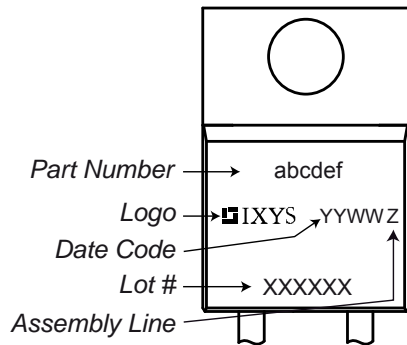
Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEP15-06A	DSEP15-06A	Tube	50	473529

Similar Part	Package	Voltage class
DSEP15-06B	TO-220AC (2)	600

Equivalent Circuits for Simulation   *on die level* $T_{VJ} = 175°C$

I → V_0 → R_0

		Fast Diode	
$V_{0\,max}$	threshold voltage	0.99	V
$R_{0\,max}$	slope resistance *	12	mΩ

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Outlines   TO-220
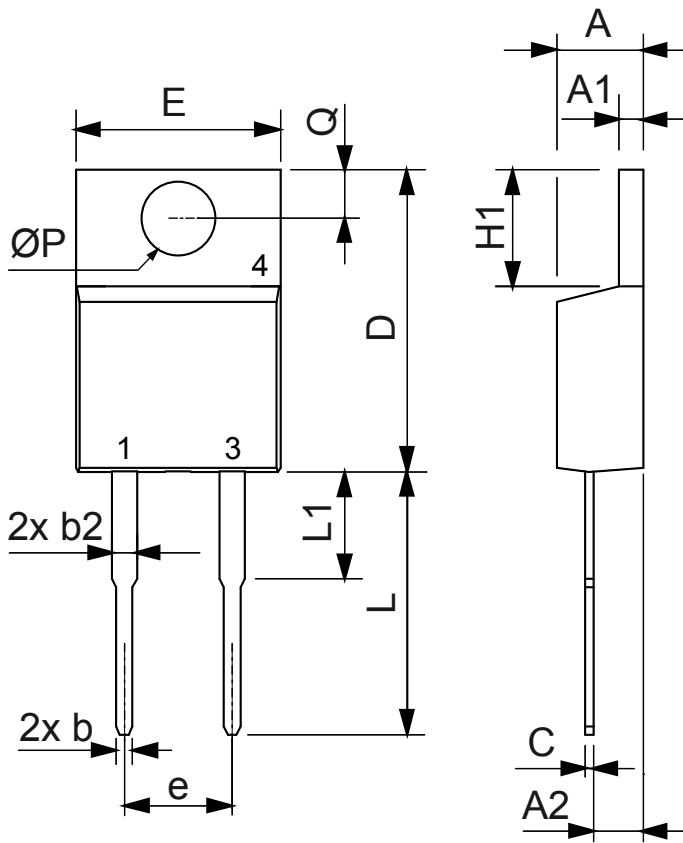
Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.32	4.82	0.170	0.190
A1	1.14	1.39	0.045	0.055
A2	2.29	2.79	0.090	0.110
b	0.64	1.01	0.025	0.040
b2	1.15	1.65	0.045	0.065
C	0.35	0.56	0.014	0.022
D	14.73	16.00	0.580	0.630
E	9.91	10.66	0.390	0.420
e	5.08	BSC	0.200	BSC
H1	5.85	6.85	0.230	0.270
L	12.70	13.97	0.500	0.550
L1	2.79	5.84	0.110	0.230
ØP	3.54	4.08	0.139	0.161
Q	2.54	3.18	0.100	0.125

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IXYS reserves the right to change limits, conditions and dimensions.   Data according to IEC 60747and per semiconductor unless otherwise specified   20120318a

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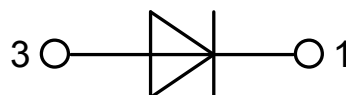
Fast Diode
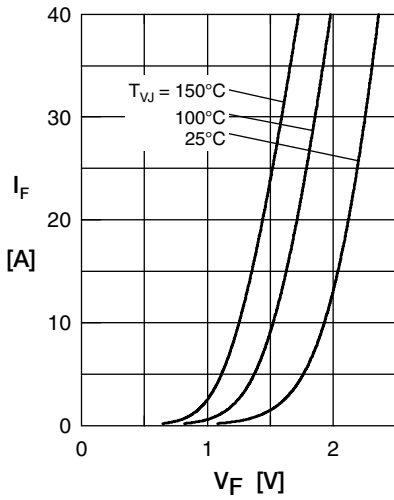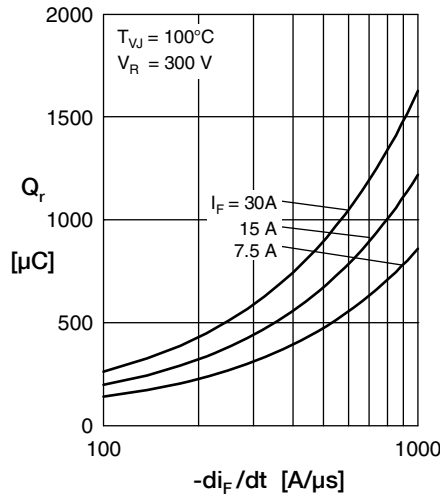

Fig. 1 Forward current
I_F versus V_F

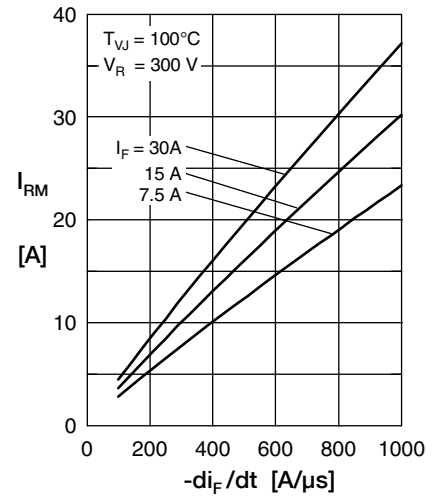Fig. 2 Typ. reverse recov. charge
Q_r versus $-di_F/dt$

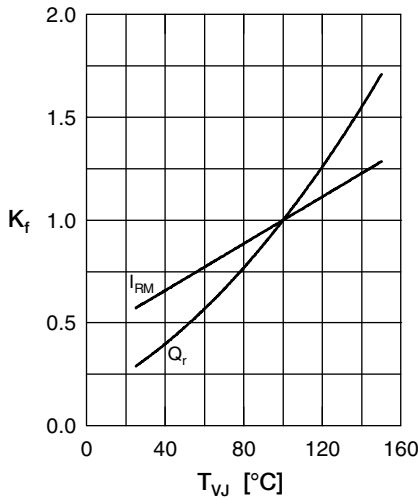Fig. 3 Typ. peak reverse current
I_{RM} versus $-di_F/dt$

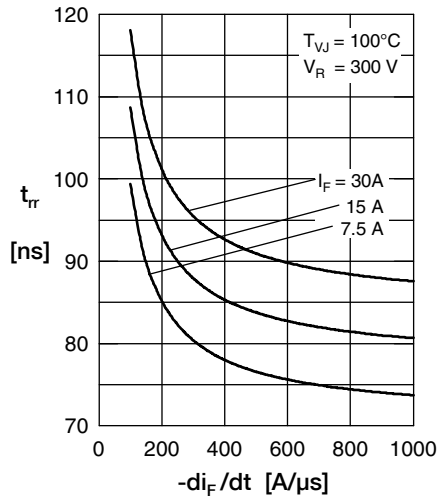

Fig. 4 Dynamic parameters
Q_r, I_{RM} versus T_{VJ}
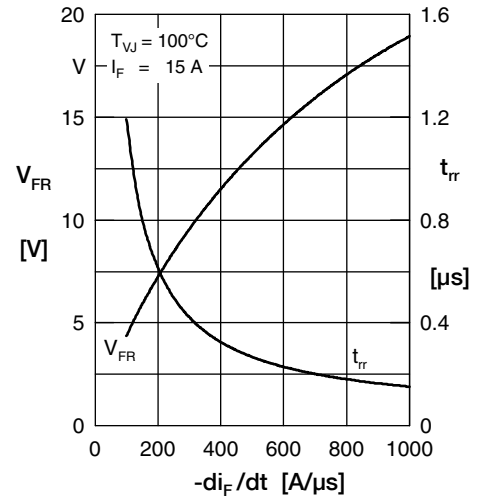

Fig. 5 Typ. recovery time
t_{rr} versus $-di_F/dt$

Fig. 6 Typ. peak forward voltage
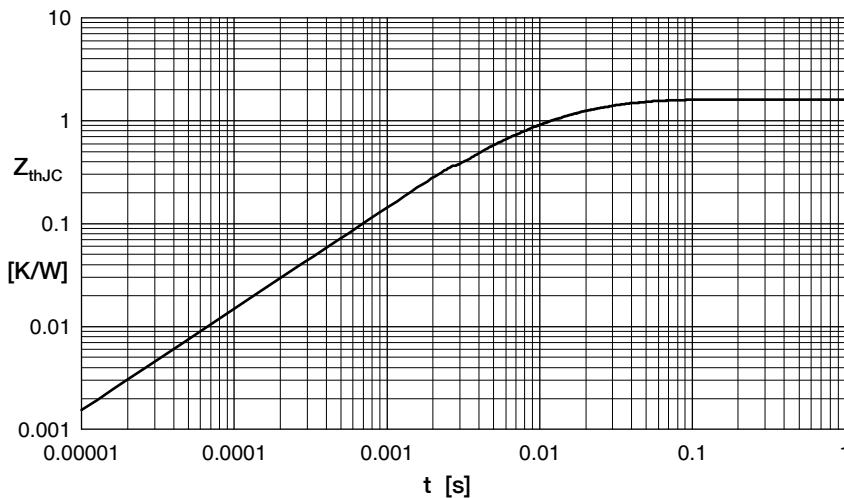V_{FR} and t_{fr} versus di_F/dt

Fig. 7 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.908	0.0052
2	0.350	0.0003
3	0.342	0.017